

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

QFN 6mm X 6mm Exp. Pad

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**TOTAL MASS (g) : 0.10711**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.006570	1000000	61338.8828125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.043661	975000	407628.15625		
		Iron (Fe)	7439-89-6	0.001075	24000	10036.4228516		
		Phosphorus (P)	7723-14-0	0.000013	300	121.370689392		
		Zinc (Zn)	7440-66-6	0.000031	700	289.422424316		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.044780</b>	<b>1000000</b>	<b>418075.375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.004194	1000000	39154.9414062		
		<b>External Plating Total:</b>				<b>0.004194</b>	<b>1000000</b>	<b>39154.9414062</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000108	1000000	1008.31036377		
<b>Internal Plating Total:</b>				<b>0.000108</b>	<b>1000000</b>	<b>1008.31036377</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000024	50000	224.068984985		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000143	300000	1335.07763672		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000309	650000	2884.88818359		
<b>Die Attach Total:</b>				<b>0.000476</b>	<b>1000000</b>	<b>4444.03466797</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006540	130000	61058.796875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.043267	860000	403949.6875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000503	10000	4696.11230469		
		<b>Encapsulation Total:</b>				<b>0.050310</b>	<b>1000000</b>	<b>469704.59375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000672	1000000	6273.93115234		
					<b>TOTAL MASS (g) :</b>	<b>0.10711</b>		